



N-Channel 25 V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A) ^a	Q _g (Typ.)		
25	0.0027 at V _{GS} = 10 V	36	49 nC		
	0.0033 at V _{GS} = 4.5 V	29			

SO-8 S 1 S 2 T D S 3 G 4 SO-8

Top View

Ordering Information: Si4632DY-T1-E3 (Lead (Pb)-free)

Si4632DY-T1-GE3 (Lead (Pb)-free and Halogen-free)

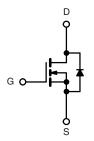
FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- Low Q_{gd}
- 100 % R_g Tested
- UIS and Capacitance Tested
- Compliant to RoHS Directive 2002/95/EC



APPLICATIONS

- · Synchronous Buck Low Side
 - Notebook
 - Server
 - Workstation
- Synchronous Rectifier POL



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS	(T _A = 25 °C, un	less otherwi	se noted)		
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	25	V	
Gate-Source Voltage	V_{GS}	± 16	V		
	$T_C = 25 ^{\circ}C$	_	40		
Continuous Drain Current (T _J = 150 °C)	T _C = 70 °C		32		
Continuous Diain Curient (1) = 130 C)	T _A = 25 °C	l _D	27 ^{b, c}		
	T _A = 70 °C		21 ^{b, c}	A	
Pulsed Drain Current		I _{DM}	70	_ A	
Continuous Source-Drain Diode Current	T _C = 25 °C	I-	7.0		
Continuous Source-Dialit Diode Current	T _A = 25 °C	l _S	3.0 ^{b, c}		
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	30		
Avalanche Energy	L = 0.1 IIII	E _{AS}	45	mJ	
	T _C = 25 °C		7.8		
Maximum Power Dissipation	T _C = 70 °C	ь	5.0	w	
waxiinaiii i owei Dissipatioii	T _A = 25 °C	- P _D	3.5 ^{b, c}	VV	
	T _A = 70 °C		2.2 ^{b, c}		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{b, d}	t ≤ 5 s	R _{thJA}	29	35	°C/W	
Maximum Junction-to-Foot (Drain)	Steady	R_{thJF}	13	16]	

Notes:

- a. Based on T_C = 25 °C.
- b. Surface mounted on 1" x 1" FR4 board.
- c. t = 5 s.
- d. Maximum under steady state conditions is 125 $^{\circ}\text{C/W}.$

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	25			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	J 050 A		23			
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	l _D = 250 μA		- 6		mV/°C	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.2		2.6	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 16 \text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 25 V, V _{GS} = 0 V			1	μΑ	
		V _{DS} = 25 V, V _{GS} = 0 V, T _J = 55 °C			10		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} = \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	30			Α	
Drain-Source On-State Resistance ^a	В	V _{GS} = 10 V, I _D = 20 A		0.0022	0.0027	Ω	
	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 15 \text{ A}$		0.0027	0.0033		
Forward Transconductance ^a	9 _{fs}	$V_{DS} = 15 \text{ V}, I_D = 20 \text{ A}$		73		S	
Dynamic ^b							
Input Capacitance	C _{iss}		3275	7450	11175		
Output Capacitance	C _{oss}	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	495	990	1485	pF	
Reverse Transfer Capacitance	C _{rss}		230	460	690		
Total Cata Charga	Qg	$V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$		108	161	nC	
Total Gate Charge				49	73		
Gate-Source Charge	Q _{gs}	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 20 \text{ A}$		19			
Gate-Drain Charge	Q _{gd}			11			
Gate Resistance	R_{g}	f = 1 MHz		1.3	2.0	Ω	
Turn-On Delay Time	t _{d(on)}			42	65		
Rise Time	t _r	$V_{DD} = 15 \text{ V}, R_{L} = 1.5 \Omega$		115	175		
Turn-Off DelayTime	t _{d(off)}	$I_D \cong 10 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		55	85		
Fall Time	t _f			14	23	20	
Turn-On Delay Time	t _{d(on)}			20	30	ns	
Rise Time	t _r	$V_{DD} = 15 \text{ V}, R_{L} = 1.5 \Omega$		69	105		
Turn-Off DelayTime	t _{d(off)}	$I_D \cong 10 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		58	90		
Fall Time	t _f			8	15		
Drain-Source Body Diode Characterist	ics						
Continous Source-Drain Diode Current	I _S	T _C = 25 °C			7	А	
Pulse Diode Forward Current ^a	I _{SM}				70		
Body Diode Voltage	V _{SD}	I _S = 3 A		0.75	1.1	V	
Body Diode Reverse Recovery Time	t _{rr}			44	70	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	1 10 A dl/dt 100 A/:- T 05 00		42	65	nC	
Reverse Recovery Fall Time	t _a	$I_F = 13 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		22			
Reverse Recovery Rise Time	t _b			22		ns	

Notes:

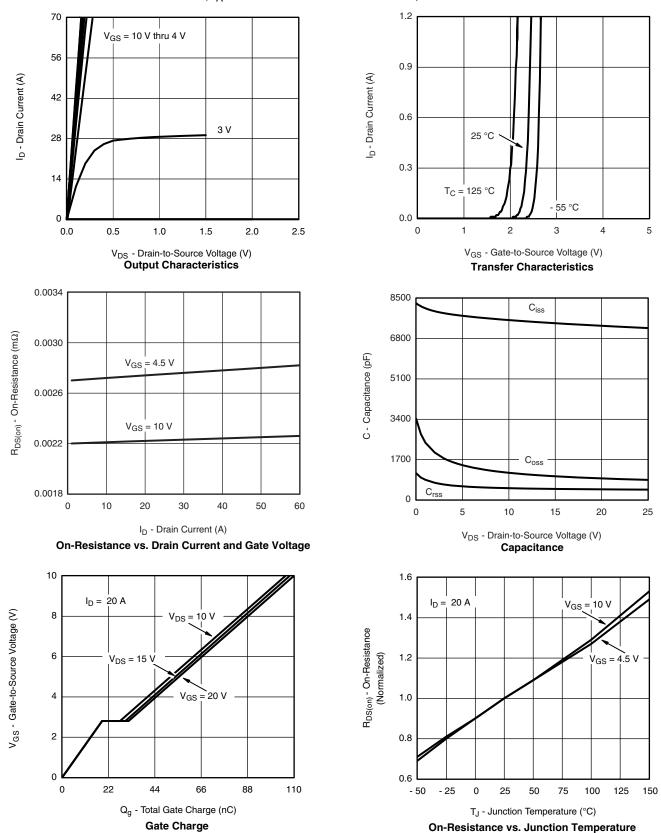
- a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



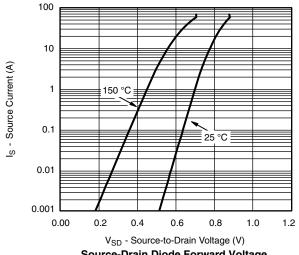


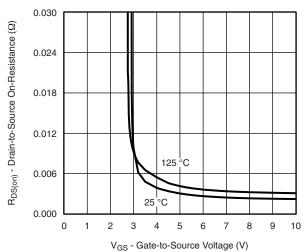
TYPICAL CHARACTERISTICS ($T_A = 25$ °C, unless otherwise noted)



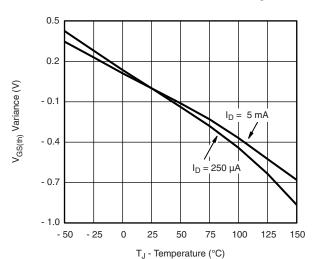
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TYPICAL CHARACTERISTICS ($T_A = 25$ °C, unless otherwise noted)



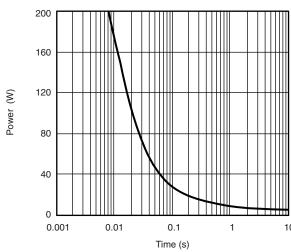


Source-Drain Diode Forward Voltage

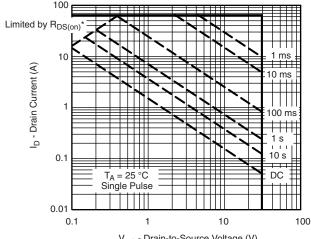


Threshold Voltage

On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient

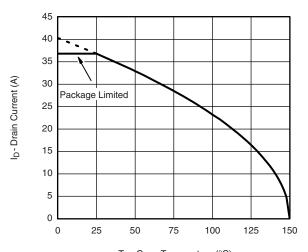


V_{DS} - Drain-to-Source Voltage (V) * V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area, Junction-to-Ambient

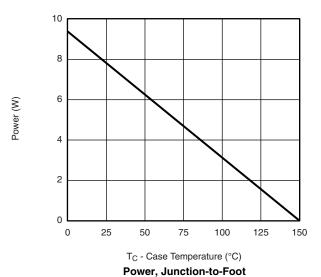


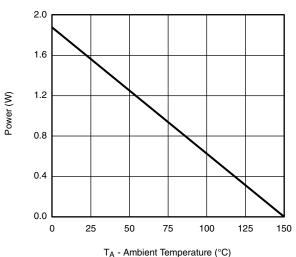
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 T_{C} - Case Temperature (°C)

Current Derating*





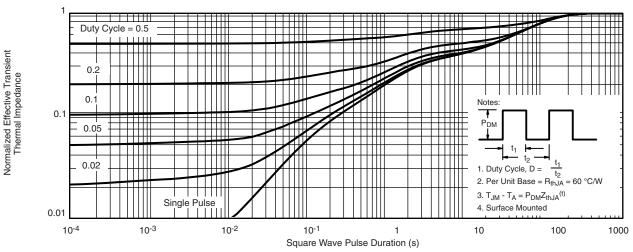
Power, Junction-to-Ambient

^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit

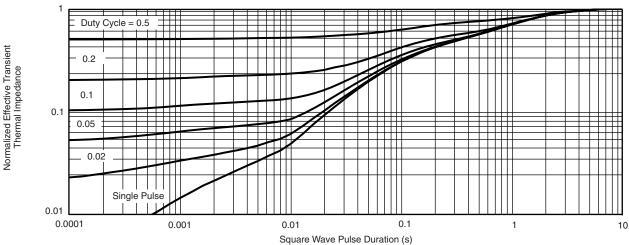
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TYPICAL CHARACTERISTICS ($T_A = 25$ °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

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